

<b>Notice of References Cited</b>	Application/Control No. 10/804,737	Applicant(s)/Patent Under Reexamination ICHITSUBO ET AL.	
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**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
	C	US-			
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**FOREIGN PATENT DOCUMENTS**

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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Tie Wang et al., Assessment of Flip Chip Assembly and Reliability via Reflowable Undefill, 2001, IEEE, 2001 Electronic Components and Technology Conference.
	V	
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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